

2.5MHz, Synchronous Boost Regulator with Bypass Mode

General Description

The RT4803 allows systems to take advantage of new battery chemistries that can supply significant energy when the battery voltage is lower than the required voltage for system power ICs. By combining built-in power transistors, synchronous rectification, and low supply current; this IC provides a compact solution for systems using advanced Li-lon battery chemistries.

The RT4803 is a boost regulator designed to provide a minimum output voltage from a single-cell Li-lon battery, even when the battery voltage is below system minimum. In boost mode, output voltage regulation is guaranteed to a maximum load current of 2A. Quiescent current in Shutdown Mode is less than $1\mu A,$ which maximizes battery life. The regulator transitions smoothly between Bypass and normal Boost Mode. The device can be forced into Bypass Mode to reduce quiescent current.

The RT4803 is available in the WL-CSP-16B 1.67x1.67 (BSC) package.

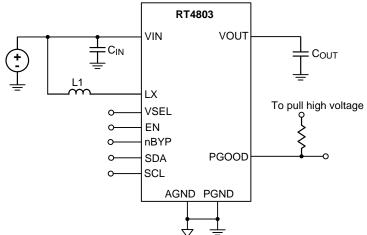
Features

- 4 Few External Components: 0.47μH Inductor and 0603 Case Size Input and Output Capacitors
- Input Voltage Range: 1.8V to 5V
- Output Range from 2.85V to 4.4V
 - ▶ VSEL = L 3.3V
 - ▶ VSEL = H 3.55V
- Maximum Continuous Load Current: 2A at V_{IN} > 2.65V Boosting V_{OUT} to 3.35V
- Up to 96% Efficient
- True Bypass Operation when V_{IN} > Target V_{OUT}
- Internal Synchronous Rectifier
- Soft-Start with True Load Disconnect
- Forced Bypass Mode
- V_{SEL} Control to Optimize Target V_{OUT}
- Short-Circuit Protection
- I²C Controlled Interface
- Ultra low Operating Quiescent Current
- Small WL-CSP 16B Package
- Discharge Function

Applications

- Single-Cell Li-Ion, LiFePO4 Smart-Phones or Tablet
- 2.5G/3G/4G Mini-Module Data Cards

Simplified Application Circuit



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Ordering Information

Pin Configurations

RT4803 🗖

└-Package Type

WSC: WL-CSP-16B 1.67x1.67 (BSC)

Note:

Richtek products are:

- ▶ RoHS compliant and compatible with the current requirements of IPC/JEDEC J-STD-020.
- ▶ Suitable for use in SnPb or Pb-free soldering processes.

(A2) EN PGOOD VIN VIN (B1) (B2) (B3) (B4) VŠEL ŠČL VOUT VOUT (C1) (C2) (C4) nBYP SDA ĽΧ (D2)

(TOP VIEW)

WL-CSP-16B 1.67x1.67 (BSC)

AĞND PĞND PĞND PĞND

Marking Information



0G: Product Code W : Date Code

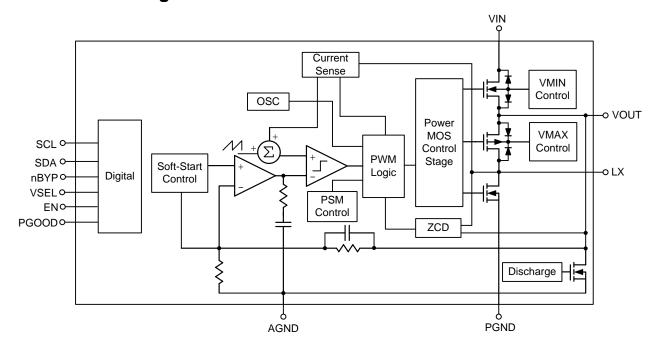
Functional Pin Description

| Pin No. | Pin Name | Pin Function |
|------------|----------|--|
| A1 | EN | Enable. When this pin is HIGH, the circuit is enabled. |
| A2 | PGOOD | Power Good. It is a open-drain output. PGOOD pin pulls low automatically if the overload or OTP event occurs. |
| A3, A4 | VIN | Input Voltage. Connect to Li-Ion battery input power source. |
| B1 | VSEL | Output Voltage Select. When boost is running, this pin can be used to select output voltage |
| B2 | SCL | Serial Interface Clock. (Pull down if I ² C is non-used). |
| B3, B4 | VOUT | Output Voltage. Place C _{OUT} as close as possible to the device. |
| C1 | nBYP | Bypass. This pin can be used to activate Forced Bypass Mode. When this pin is LOW, the bypass switches are turned on and the IC is otherwise inactive. |
| C2 | SDA | Serial Interface Date Line. (Pull down if I ² C is non-used). |
| C3, C4 | LX | Switching node. Connect to inductor. |
| D1 | AGND | Analog Ground. This is the signal ground reference for the IC. All voltage levels are measured with respect to this pin. |
| D2, D3, D4 | PGND | Power Ground. This is the power return for the IC. The Cout bypass capacitor should be returned with the shortest path possible to these pins. |

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Function Block Diagram





Operation

RT4803 combined built-in power transistors, synchronous rectification, and low supply current, it provides a compact solution for system using advanced Li-lon battery chemistries.

In boost mode, output voltage regulation is guaranteed to a maximum load current of 2A. Quiescent current in Shutdown mode is less than 1 μ A, which maximizes battery life.

| Mode | | Depiction | Condition | | |
|--------|-------|------------------|------------------------------------|--|--|
| LIN | LIN 1 | Linear startup 1 | V _{IN} > V _{OUT} | | |
| LIIN | LIN 2 | Linear startup 2 | V _{IN} > V _{OUT} | | |
| Soft- | Start | Boost soft-start | Vout < Vout(min) | | |
| Boost | | Boost mode | Vout = Vout(min) | | |
| Bypass | | Bypass mode | $V_{IN} > V_{OUT(MIN)}$ | | |

LIN State

When V_{IN} is rising, it enters the LIN State. There are two parts for the LIN state. It provides maximum current for 1A to charge the C_{OUT} in LIN1, and the other one is for 2A in LIN2. By the way, the EN is pulled high and $V_{IN} > UVLO$.

As the figure shown, if the timeout is over the specification, it will enter the Fault mode.

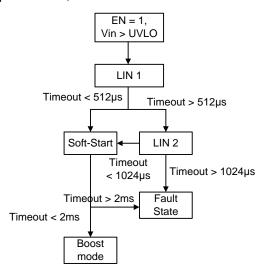


Figure 1. RT4803 State Chart

Startup and Shutdown State

When V_{IN} is rising and through the LIN state, it will enter the Startup state. If EN is pulled low, any function is turned-off in shutdown mode.

Soft-Start State

It starts to switch in Soft-start state. After the LIN state, output voltage is rising with the internal reference voltage.

There is a point, it will go to fault condition, if the large output capacitor is used and the timeout is over 2ms after the soft-start state.

Fault State

As the Figure 1 shown, it will enter to the Fault state as below.

- ▶ The timeout of LIN2 is over the 1024µs.
- ▶ It is over the 2ms when the state changed from Soft-start state to Boost mode.

It will be the high impedance between the input and output when the fault is triggered. A restart will be start after 1ms.

Boost Mode

There are two normal operation modes, one is the Boost mode, and the other one is Bypass mode. In the Boost mode, it provides the power to load by internal synchronous switches after the soft-start state.

Bypass Mode

In Bypass mode, the differential voltage between V_{IN} and V_{OUT} is 250mV. Output voltage will increase when the input voltage is rising after the soft-start state.

Bypass Mode Operation

In automatic mode, it transits from Boost mode to Bypass mode. As the Figure 2 shown, there are three MOSFET (Q1 to Q3). The Q1 & Q2 is for Boost mode, it is used by Q3 for Bypass mode. V_{OUT} will be followed the V_{IN} when V_{IN} is higher than the target output voltage. As the Figure 3 shown, it is transited by bypass MOSFET (Q3). V_{OUT} followed the V_{IN} .

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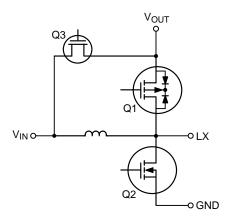


Figure 2. Boost Converter With Bypass Mode

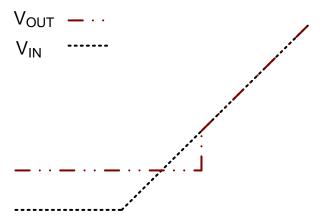


Figure 3. RT4803 mode changed

Force Pass-Through Mode

When EN pulled high and nBYP pulled low. The device is active in the Force pass-through mode. It supplies current is approximately 15 μ A typ. From the battery, the device is short circuit protected by a current limit of 4000mA.

VSEL

It is concerned the minimum output voltage at the heavy load condition. There are two output voltage levels (3.3V & 3.55V) in Boost mode and Bypass mode. It can be selected by VSET, so it must not be floating.

PGOOD (Power Good)

Power good is a open-drain input. If it is 0, it stands for fault occurred. The power good provide the information to show the state of the system,

- PGOOD pin show high when the sequence of soft-start is completed.
- Any fault cause PGOOD to be pulled low.
- PGOOD low when PMIS current limit has triggered for OR the die the temperature exceeds 120°C.
 PGOOD is re-asserted when the device cools below to 100°C.

OCP

The converter senses the current signal when the high-side P-MOSFET turns on. As a result, the OCP is cycle by-cycle current limitation. If the OCP occurs, the converter holds off the next on pulse until inductor current drops below the OCP limit.

OTP

The converter has an over-temperature protection. When the junction temperature is higher than the thermal shutdown rising threshold, the system will be latched and the output voltage will no longer be regulated until the junction temperature drops under the falling threshold.

EN & nBYP

It is used to select mode. As the table 1 shown, there are four device states. When EN and nBYP both pull high, RT4803 is normal operation and enter automatic mode.

If the EN pull low, and nBYP pull high/low, RT4803 is forced in shut-down mode and the quiescent is less than $1\mu A$. It works in force pass-through mode, if the EN set high and nBYP set low.

Discharge

RT4803 features the discharge function to release the output power when the EN pin goes low condition.

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Table 1

| EN input | nBYP Input | Device State |
|----------|------------|--|
| 0 | 0/1 | The device is shut down and the shut down current is down to $1\mu A$. |
| 1 | 0 | The device is active in forced pass-through mode. The device supply current is approximately 15 μ A typ. From the battery. The device is short circuit protected by a current limit of ca. 4000mA. |
| 1 | 1 | The device is active in auto mode (dc/dc boost, pass-through mode) The device supply current is approximately 65µA typ. from the battery |



| Absolute Maximum Ratings (Note 1) | |
|---|---------------------|
| VIN, VOUT to AGND | -0.2V to 6V |
| • EN, VSEL, PGOOD, nBYP to AGND | -0.2V to 6V |
| • LX | (PGND - 0.2V) to 6\ |
| Power Dissipation, P_D @ T_A = 25°C | |
| WL-CSP-16B 1.67x1.67 (BSC) | 2.09W |
| Package Thermal Resistance (Note 2) | |
| WL-CSP-16B 1.67x1.67 (BSC), θJA | 47.7°C/W |
| Lead Temperature (Soldering, 10 sec.) | 260°C |
| Junction Temperature | 150°C |
| Storage Temperature Range | –65°C to 150°C |
| • ESD Susceptibility (Note 3) | |
| HBM (Human Body Model) | 2kV |
| MM (Machine Model) | 200V |
| CDM (Charge Device Model) | 1kV |
| Recommended Operating Conditions (Note 4) | |
| Input Voltage Range | 1.8V to 5V |
| Output Voltage Range | 2.85V to 4.4V |
| Ambient Temperature Range | −40°C to 85°C |
| Junction Temperature Range | -40°C to 125°C |

Electrical Characteristics

(V_{IN} = 3V, V_{OUT} = 3.55V, T_A = 25°C, unless otherwise specified)

| Parameter | Symbol | Test Conditions | Min | Тур | Max | Unit |
|---|--------------------|---|-----|-----|-----|------|
| VIN Operation Range | Vin | | 1.8 | | 5 | V |
| VIN Quiescent Current | IQ | Auto Bypass Mode, V _{IN} = 3.8V | | 40 | 70 | μΑ |
| VIN Quiescent Current | IQ | Boost mode, I _{LOAD} = 0mA, Switching, V _{IN} = 3V | | 65 | 100 | μА |
| VIN Quiescent Current | IQ | Force Bypass , V _{IN} = 3.6V | | 15 | 25 | μΑ |
| VIN Shutdown Current | I _{SHDN} | EN = 0V, V _{IN} = 3.6V | | | 1 | μΑ |
| VOUT to VIN Reverse Leakage | ILK | Vout = 5V, EN = nBYP = H, VIN < Vout | | 0.2 | 1 | μА |
| VOUT Discharge Impedance | R_DIS_OUT | EN = L | | 80 | | Ω |
| Under Voltage Lock Out | V _U VLO | V _{IN} Rising | | 1.6 | 1.8 | V |
| Under Voltage Lock Out Hysteresis | Vuvlo_HYS | | | 200 | | mV |
| PGOOD Low | V _{PGOOD} | I _{PGOOD} = 5mA | | | 0.4 | V |
| PGOOD Leakage Current | IPGOOD_LK | VPGOOD = 5V | | | 1 | μΑ |
| Logic Level High EN, VSEL, nBYP, SCL, SDA | ViH | | 1.2 | | | V |

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RT4803



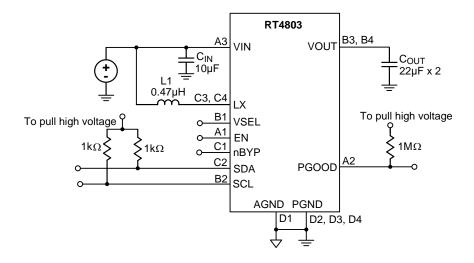
| Parameter | Symbol | Test Conditions | Min | Тур | Max | Unit |
|---|----------------------|---|-----|------|-----|------|
| Logic Level Low EN, VSEL, nBYP, SCL, SDA | VIL | | | | 0.4 | V |
| Output Voltage Accuracy | V _{REG} | V _{OUT} – V _{IN} > 100mV, PWM | -2 | | 2 | % |
| Minimum On Time | T _{ON} | V _{IN} = 3V, V _{OUT} = 3.5V, I _{LOAD} > 1000mA | | 80 | | ns |
| Maximum Duty Cycle | DMAX | | 40 | | | % |
| Switching Frequency | Fsw | V _{IN} = 2.65V, V _{OUT} = 3.5V, I _{LOAD} = 1000mA | 2 | 2.5 | 3 | MHz |
| Boost Valley Current Limit | I _{CL} | V _{IN} = 2.9V | 4.4 | 5 | 5.6 | Α |
| Soft-Start Input Current Limit | ISS_PK | LIN1 | | 1000 | | mΑ |
| Soft-Start Input Current Limit | ISS_PK | LIN2 | | 2000 | | mA |
| Pass Through Mode Current Limit | IBPCL | V _{IN} = 3.2V | | 4 | | Α |
| N-channel Boost Switch RDS(ON) | RDSN | V _{IN} = 3.2V, V _{OUT} = 3.5V | | 60 | 95 | mΩ |
| P-channel Boost Switch RDS(ON) | RDSP | V _{IN} = 3.2V, V _{OUT} = 3.5V | | 40 | 80 | mΩ |
| N-channel Bypass Switch RDS(ON) | R _{DSP_BYP} | V _{IN} = 3.2V, V _{OUT} = 3.5V | | 40 | 60 | mΩ |
| Hot Die Trigger Threshold | T _{HD} | | | 100 | | °C |
| Hot Die Release Threshold | T _{HDR} | | | 90 | | °C |
| Over Temperature Protection | T _{OTP} | | | 160 | | °C |
| Over Temperature Protection Hysteresis | T _{OTP_HYS} | | | 20 | 1 | °C |
| FAULT Restart Time | T _{RST} | | | 1 | 1 | ms |

Note 1. Stresses beyond those listed "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

- Note 2. θ_{JA} is measured at $T_A = 25$ °C on a high effective thermal conductivity four-layer test board per JEDEC 51-7.
- Note 3. Devices are ESD sensitive. Handling precaution recommended.
- **Note 4.** The device is not guaranteed to function outside its operating conditions.



Typical Application Circuit



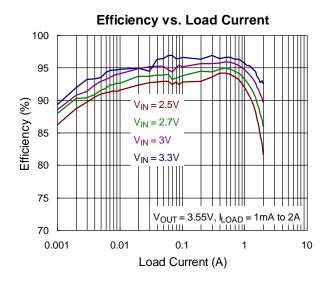
BOM of Test Board

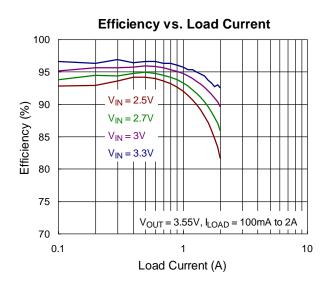
| Reference | Description | Manufacturer | Package | Parameter | Тур. | Unit |
|-----------------|---------------|------------------------|---------|----------------|------|------|
| C _{IN} | 10μF/16V/X5R | Taiyo : EMK212ABJ106KG | 0805 | С | 10 | μF |
| Соит | 22μF/10V/X5R | Taiyo : LMK212BBJ226MG | 0805 | С | 22 | μF |
| 1.1 | 0.47.14 +200/ | TOVO : DEE2520E D47M | 2520 | L | 0.47 | μН |
| L1 (| 0.47µH, ±20% | TOKO: DFE2520F-R47M | 2520 | DCR (Series R) | 29 | mΩ |

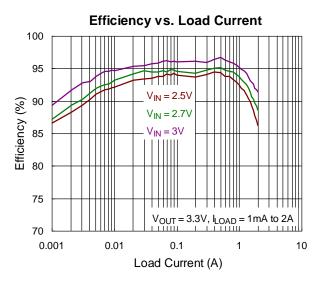
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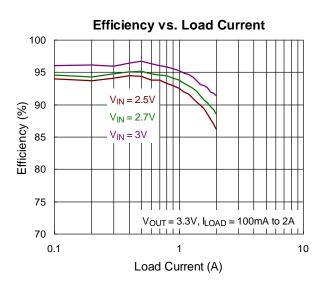


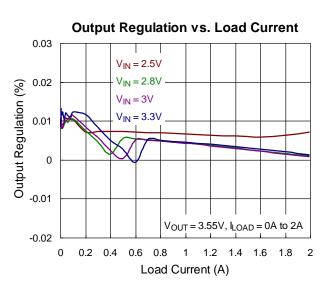
Typical Operating Characteristics

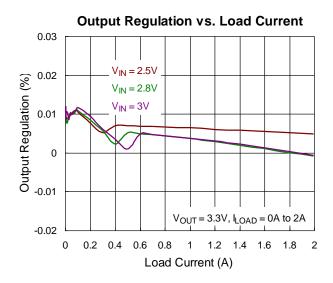


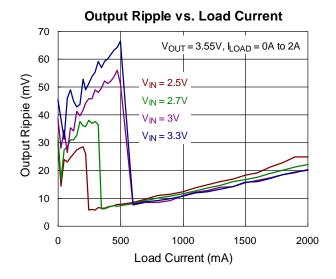


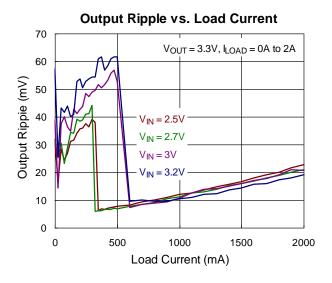


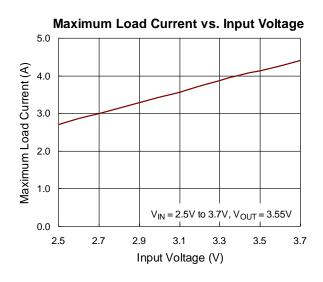


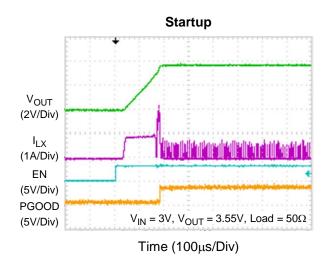


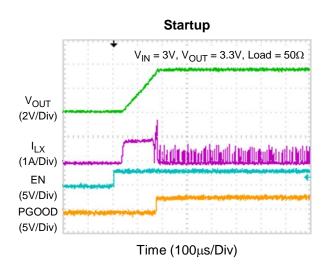


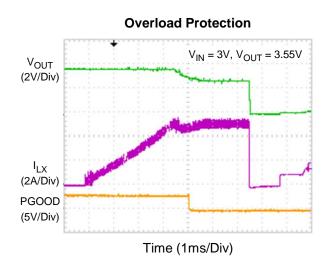






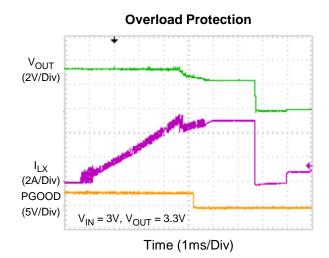


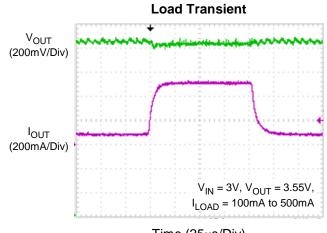




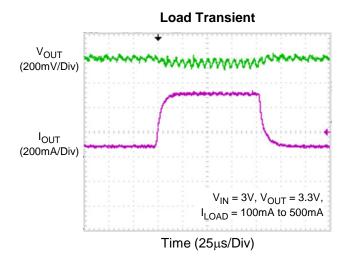
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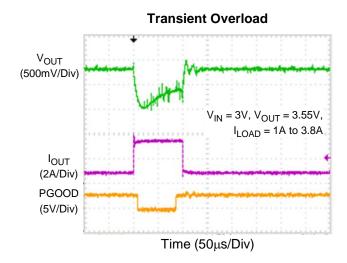


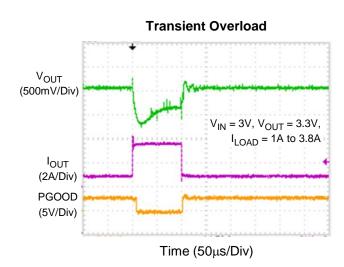




Time (25µs/Div)









Application Information

Enable

The device can be enabled or disabled by the EN pin. When the EN pin is higher than the threshold of logic-high, the device starts operating with soft-start. Once the EN pin is set at low, the device will be shut down. In shutdown mode, the converter stops switching, internal control circuitry is turned off, and the load is disconnected from the input. This also means that the output voltage can drop below the input voltage during shutdown.

Soft-Start State

After the successful completion of the LIN state ($V_{OUT} \ge V_{IN} - 300 \text{mV}$).

During Soft-Start state, V_{OUT} is ramped up by Boost internal loop. If V_{OUT} fails to reach target value during the Soft-Start period for more than 2ms, a fault condition is declared.

Output Voltage Setting

User can select the output voltage level by VSEL and I2C. If the VSEL pulled low, the default is 3.3V, and if it pulled high, the default is 3.55V.

The output voltage range is from 2.85V to 4.4V.

Power Save Mode

PSM is the way to improve efficiency at light load.

When the output voltage is lower than a set threshold voltage, the converter will operate in PSM.

It raises the output voltage with several pulses until the loop exits PSM.

Under-Voltage Lockout

The under-voltage lockout circuit prevents the device from operating incorrectly at low input voltages. It prevents the converter from turning on the power switches under undefined conditions and prevents the battery from deep discharge. VIN voltage must be greater than 1.7V to enable the converter. During operation, if VIN voltage drops below 1.6V, the converter is disabled until the supply exceeds the UVLO rising threshold. The RT4803 automatically

restarts if the input voltage recovers to the input voltage UVLO high level.

Thermal Shutdown

The device has a built-in temperature sensor which monitors the internal junction temperature. If the temperature exceeds the threshold, the device stops operating. As soon as the IC temperature has decreased below the threshold with a hysteresis, it starts operating again. The built-in hysteresis is designed to avoid unstable operation at IC temperatures near the over temperature threshold.

Inductor Selection

The recommended nominal inductance value is $0.47 \mu H.$

It is recommended to use inductor with dc saturation current ≥ 3500mA

Input Capacitor Selection

At least a $10\mu F$ input capacitor is recommended to improve transient behavior of the regulator and EMI behavior of the total power supply circuit for LX. And at least a $1\mu F$ ceramic capacitor placed as close as possible to the VIN and GND pins of the IC is recommended.

Output Capacitor Selection

At least $22\mu F$ x 2 capacitors is recommended to improve V_{OUT} ripple.

Output voltage ripple is inversely proportional to COUT.

Output capacitor is selected according to output ripple which is calculated as:

$$\begin{split} &V_{RIPPLE(P-P)} = t_{ON} \times \frac{I_{LOAD}}{C_{OUT}} \\ &\text{and} \\ &t_{ON} = t_{SW} \times D = t_{SW} \times \left(1 - \frac{V_{IN}}{V_{OUT}}\right) \\ &\text{therefore}: \\ &C_{OUT} = t_{SW} \times \left(1 - \frac{V_{IN}}{V_{OUT}}\right) \times \frac{I_{LOAD}}{V_{RIPPLE(P-P)}} \\ &\text{and} \\ &t_{SW} = \frac{1}{f_{SW}} \end{split}$$

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The maximum V_{RIPPLE} occurs when V_{IN} is at minimum and ILOAD is at maximum.

Output Discharge Function

With the EN pin set to low, the VOUT pin is internally connected to GND by an internal discharge N-MOSFET switch.

This feature prevents residual charge voltages on capacitor connected to VOUT pins, which may impact proper power up of the system.

Current Limit

RT4803 employs a valley-current limit detection scheme to sense inductor current during the off-time. When the loading current is increased such that the loading is above the valley current limit threshold, the off-time is increased until the current is decreased to valley-current threshold. Next on-time begins after current is decreased to valley-current threshold. On-time is decided by (Vout - Vin) / Vout ratio. The output voltage decreases when further loading current increase. As the following figure shown, the current limit function is implemented by the scheme.

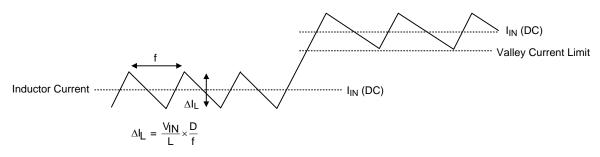


Figure 4. Inductor Currents In Current Limit Operation

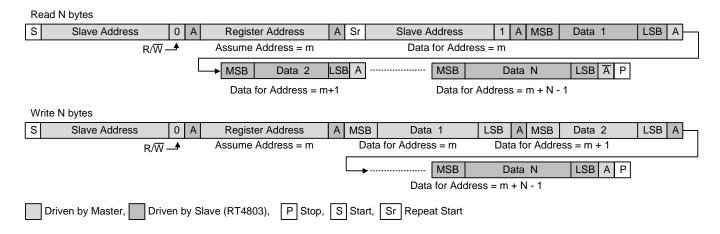


Register Table Lists [Slave address = 1110101 (0x75)]

| Name | Address | Description |
|-----------|---------|---|
| CONFIG | 0x01 | MODE control & Spread modulation control |
| VOUTFLOOR | 0x02 | Output Voltage Selection |
| VOUTROOF | 0x03 | Output Voltage Selection |
| ILIMSET | 0x04 | Set current limit & Softstart current limit |
| STATUS | 0x05 | Read IC status |

I²C Interface

The RT4803 I²C slave address is 1110101 (7bits). The I²C interface supports fast mode (bit rate up to 400kb/s). The write or read bit stream $(N \ge 1)$ is shown below :



RT4803



| Off | set 0x01 | | | | CONFIG | | | |
|-------|-------------|-----------|-----------|------------|-----------|---------|------------------|------------------|
| Bits | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| Name | RESET | ENABLE<1> | ENABLE<0> | RESERVED | RESERVED | SSFM | MODE_CTRL <1> | MODE_CTRL <0> |
| Reset | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 |
| Туре | RW | RW | RW | RW | RW | RW | RW | RW |
| Off | set 0x02 | | | | VOUTFLOOR | | | |
| Bits | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| Name | RESERVED | RESERVED | RESERVED | VSEL<4> | VSEL<3> | VSEL<2> | VSEL<1> | VSEL<0> |
| Reset | 0 | 0 | 0 | 0 | 1 | 0 | 0 | 1 |
| Туре | RW | RW | RW | RW | RW | RW | RW | RW |
| Off | set 0x03 | | VOUTROOF | | | | | |
| Bits | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| Name | RESERVED | RESERVED | RESERVED | VSEL<4> | VSEL<3> | VSEL<2> | VSEL<1> | VSEL<0> |
| Reset | 0 | 0 | 0 | 0 | 1 | 1 | 1 | 0 |
| Type | RW | RW | RW | RW | RW | RW | RW | RW |
| Off | set 0x04 | | | | ILIMSET | | | |
| Bits | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| Name | RESERVED | RESERVED | ILIM_OFF | SOFT_START | ILIM<3> | ILIM<2> | ILIM<1> | ILIM<0> |
| Reset | 0 | 0 | 0 | 1 | 1 | 1 | 1 | 1 |
| Type | RW | RW | RW | RW | RW | RW | RW | RW |
| Off | Offset 0x05 | | | | STATUS | | | |
| Bits | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| Name | TSD | HOTDIE | DCDCMODE | OPMODE | ILIMPT | ILIMBST | FAULT | PGOOD |
| Reset | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| Type | RO | RO | RO | RO | RO | RO | RO | RO |



| Name | | Function | Addr | |
|---------|-------|--|-------|--|
| CON | NFIG | MODE control & Spread modulation control | 0x01 | |
| Bit | Mode | name | Reset | Description |
| 7 | R/W | RESET | 0 | 0 : Disable ID detection function 1 : Enable ID detection function |
| [6:5] | R/W | ENABLE[1 : 0] | 0 | 00 : Device operation follows hardware control signal (refer to table 1) 01 : Device operation in auto transition mode (boost/bypass) regardless of the nBYP control signal (EN = 1) 10 : Device is forced in pass-through mode regardless of the nBYP control signal (EN = 1) 11 : Device is in shutdown mode. The output voltage is reduced to a minimum value (V_{IN} − V_{OUT} ≤ 3.6V) regardless of the nBYP control signal (EN = 1) |
| 4 | R/W | Reserved | 0 | |
| 3 | R/W | Reserved | 1 | |
| 2 | R/W | SSFM | 0 | Spread spectrum modulation is disabled. Spread spectrum modulation is enabled in PWM mode. |
| [1:0] | R/W | MODE_CTRL[1:0] | 01 | 00 : Device operation follows hardware control signal. 01 : PFM with automatic transition into PWM operation. 10 : Forced PWM operation. 11 : PFM with automatic transition into PWM operation (VSEL = L), forced PWM operation (VSEL = H). |
| Na | me | Function | Addr | |
| VOUTI | FLOOR | Output Voltage Selection | 0x02 | |
| Bit | Mode | name | Reset | Description |
| [7 : 5] | R/W | Reserved | 000 | |
| [4:0] | R/W | VOUT[4 : 0] | 01001 | 00000 : V _{OUT} = 2.85V 00001 : V _{OUT} = 2.9V 00010 : V _{OUT} = 2.95V 00011 : V _{OUT} = 3V 00100 : V _{OUT} = 3.05V 01001 : V _{OUT} = 3.3V (default) 11111 : V _{OUT} = 4.4V |



| Na | ıme | Function | Addr | |
|----------|------|---|-------|---|
| VOUTROOF | | Output Voltage Selection | 0x03 | |
| Bit | Mode | name | Reset | Description |
| [7 : 5] | R/W | Reserved | 000 | |
| [4:0] | R/W | VOUT[4:0] | 01110 | 00000 : V _{OUT} = 2.85V 00001 : V _{OUT} = 2.9V 00010 : V _{OUT} = 2.95V 00011 : V _{OUT} = 3V 00100 : V _{OUT} = 3.05V 01110 : V _{OUT} = 3.55V (default) 11111 : V _{OUT} = 4.4V |
| Name | | Function | Addr | |
| ILIMSET | | Set current limit & Softstart current limit | 0x04 | |
| Bit | Mode | name | Reset | Description |
| [7 : 6] | R/W | Reserved | 00 | |
| 5 | R/W | ILIM_OFF | 0 | 0 : Current Limit Enabled 1 : Current Limit Disabled |
| 4 | R/W | Soft-Start | 1 | Boost soft-start current is limited per ILIM bit settings Boost soft-start current is limited to ca. 1250mA inductor valley current |
| [3:0] | R/W | ILIM[3 : 0] | 1111 | 1000 : 1500mA 1001 : 2000mA 1010 : 2500mA 1011 : 3000mA 1100 : 3500mA 1101 : 4000mA 1110 : 4500mA 1111 : 5000mA (default) |



| Na | ıme | Function | Addr | |
|-----|---------------------------|----------|-------|---|
| STA | STATUS Read IC status 0x0 | | 0x05 | |
| Bit | Mode | name | Reset | Description |
| 7 | R | TSD | 0 | Normal operation. Thermal shutdown tripped. The flag is reset after readout. |
| 6 | R | HOTDIE | 0 | 0 : T _J < 115°C. 1 : T _J > 115°C. |
| 5 | R | DCDCMODE | 0 | Device operates in PFM mode. Device operates in PWM mode. |
| 4 | R | OPMODE | 0 | Device operates in pass-through mode. Device operates in dc/dc mode. |
| 3 | R | ILIMPT | 0 | Normal operation. Indicates that the bypass FET current limit has triggered. This flag is reset after readout. |
| 2 | R | ILIMBST | 0 | Normal operation. Indicates that the average input current limit has triggered for 1.5ms in dc/dc boost mode. This flag is reset after readout. |
| 1 | R | FAULT | 0 | O: Normal operation. I: Indicates that a fault condition has occurred. This flag is reset after readout. |
| 0 | R | PGOOD | 0 | 0 : Indicates the output voltage is out of regulation.1 : Indicates the output voltage is within its nominal range. This bit is set if the converter is forced in pass-through mode. |



Thermal Considerations

For continuous operation, do not exceed absolute maximum junction temperature. The maximum power dissipation depends on the thermal resistance of the IC package, PCB layout, rate of surrounding airflow, and difference between junction and ambient temperature. The maximum power dissipation can be calculated by the following formula:

$$P_{D(MAX)} = (T_{J(MAX)} - T_A) / \theta_{JA}$$

where $T_{J(MAX)}$ is the maximum junction temperature, T_A is the ambient temperature, and θ_{JA} is the junction to ambient thermal resistance.

For recommended operating condition specifications, the maximum junction temperature is 125°C. The junction to ambient thermal resistance, θ_{JA} , is layout dependent. For WL-CSP-16B 1.67x1.67 (BSC) package, the thermal resistance, θ_{JA} , is 47.7°C/W on a standard JEDEC 51-7 four-layer thermal test board. The maximum power dissipation at $T_A=25^{\circ}C$ can be calculated by the following formula :

 $P_{D(MAX)} = (125^{\circ}C - 25^{\circ}C) / (47.7^{\circ}C/W) = 2.09W$ for WL-CSP-16B 1.67x1.67 (BSC) package

The maximum power dissipation depends on the operating ambient temperature for fixed $T_{J(MAX)}$ and thermal resistance, θ_{JA} . The derating curve in Figure 5 allows the designer to see the effect of rising ambient temperature on the maximum power dissipation.

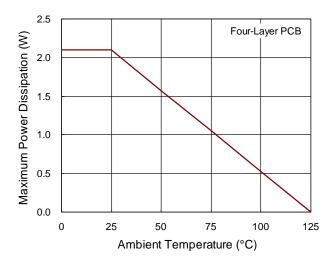


Figure 5. Derating Curve of Maximum Power

Dissipation

Layout Consideration

The PCB layout is an important step to maintain the high performance of RT4803.

Both the high current and the fast switching nodes demand full attention to the PCB layout to save the robustness of the RT4803 through the PCB layout. Improper layout might show the symptoms of poor line or load regulation, ground and output voltage shifts, stability issues, unsatisfying EMI behavior or worsened efficiency. For the best performance of the RT4803, the following PCB layout guidelines must be strictly followed.

- ▶ Place the input and output capacitors as close as possible to the input and output pins respectively for good filtering.
- ► For thermal consider, it needed to maximize the pure area for the power stage area besides the LX.

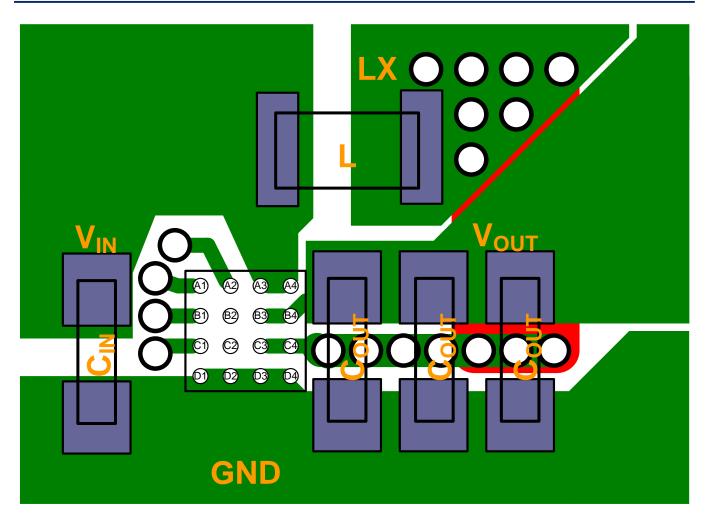
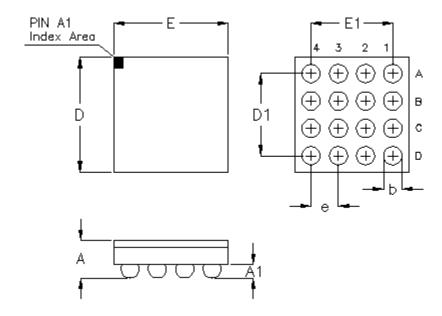


Figure 6. PCB Layout Guide



Outline Dimension



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| А | 0.500 | 0.600 | 0.020 | 0.024 |
| A1 | 0.170 | 0.230 | 0.007 | 0.009 |
| b | 0.240 | 0.300 | 0.009 | 0.012 |
| D | 1.620 | 1.720 | 0.064 | 0.068 |
| D1 | 1.200 | | 0.047 | |
| Е | 1.620 | 1.720 | 0.064 | 0.068 |
| E1 | 1.200 | | 0.047 | |
| е | 0.400 | | 0.016 | |

WL-CSP-16B 1.67x1.67 (BSC)

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EVB_RT7247AHGSP EVB_RT7252BZSP EVB_RT7280GQW EVB_RT8292AHZSP EVB_RT8297BZQW EVB_RT7231GQW

EVB_RT7232GQW EVB_RT7236GQW EVB_RT7250BZSP EVB_RT7251BZQW EVB_RT7279GQW EVB_RT8008GB RT8207MZQW

RT8296AHZSP RT9011-JGPJ6 RT8258GE RT5711AHGQW RT9081AGQZA(2) RT6154BGQW RT7238BGQUF RT5788AGJ8F

RT8812AGQW RT6278BHGQUF RT7270HZSP RD0004 RT5789AGQUF RT9076-18GVN RT9193-15GU5 RT3602AJGQW

RT8296BHZSP RT6214AHGJ6F RT9276GQW(Z00)